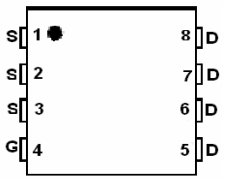
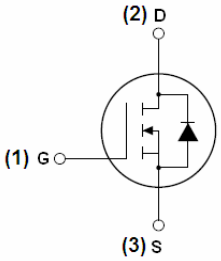
FNK N-Channel Enhancement Mode Power MOSFET

Description

The FNK10N02-A uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.



Marking and pin assignment



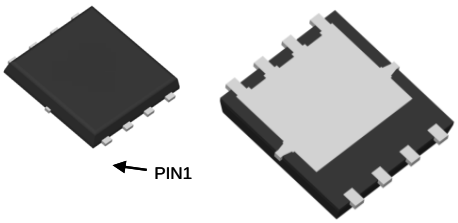
Schematic diagram

General Features

- V_{DS} =20V,I_D =180A
  $R_{DS(ON)}$ <2.25mΩ @ V_{GS}=4.5V (Typ1.95mΩ)
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation

DFN5X6

Top View **Bottom View**



Application

- Power switching application
- Load switching
- Uninterruptible power supply

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
FNK10N02	FNK10N02	DFN5*6-8L	-	-	-

Absolute Maximum Ratings (T_A=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	±12	V
Drain Current-Continuous	I_D	180	A
Drain Current-Continuous(T_C=100℃)	I_D (100℃)	154	A
Pulsed Drain Current	I_{DM}	720	A
Maximum Power Dissipation	P_D	83	W
Single pulse avalanche energy (Note 5)	E_{AS}	504	mJ
Operating Junction and Storage Temperature Range	T_J,T_{STG}	-55 To 150	℃

Thermal Characteristic

Thermal Resistance,Junction-to-Case (Note 2)	$R_{\theta JC}$	1.5	℃/W

Electrical Characteristics (T_A=25℃unless otherwise noted)

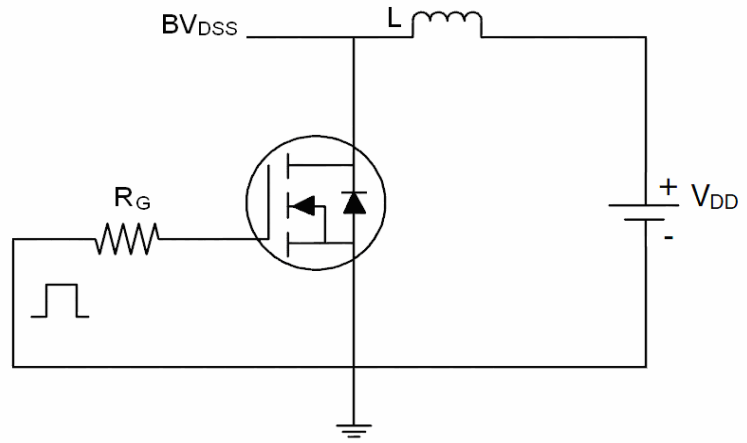
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250μA	20	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=20V,V_{GS}=0V	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	V_{GS}=±12V,V_{DS}=0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS},I_D=250μA	0.4	0.7	1	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=4.5V, I_D=20A	-	1.95	2.25	mΩ
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=2.5V, I_D=20A	-	2.05	2.6	mΩ
Forward Transconductance	g_{FS}	V_{DS}=5V,I_D=30A	100	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C_{lss}	V_{DS}=10V,V_{GS}=0V, F=1.0MHz		9585		PF
Output Capacitance	C_{oss}			1145		PF
Reverse Transfer Capacitance	C_{rss}			940		PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	VGS=10V,VDS=10V RL=0. 5Ω,RGEN=3Ω	-	12.5	-	nS
Turn-on Rise Time	t_r		-	35.5	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	40	-	nS
Turn-Off Fall Time	t_f		-	32.5	-	nS
Total Gate Charge	Q_g	VGS=4.5V,VDS=10V,ID=30A		30.4		nC
Gate-Source Charge	Q_{gs}			9.5		nC
Gate-Drain Charge	Q_{gd}			19.8		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	V_{GS}=0V,I_S=20A	-	-	1.2	V
Diode Forward Current (Note 2)	I_S	-	-	-	110	A
Reverse Recovery Time	t_{rr}	TJ = 25°C, IF = 30A di/dt = 100A/μs (Note3)	-	35.3	-	nS
Reverse Recovery Charge	Qrr		-	30.7	-	nC

Notes:

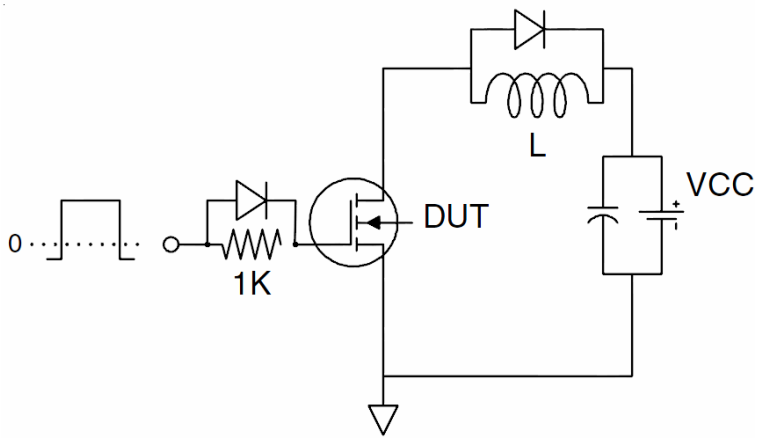
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. EAS condition：Tj=25℃,V_{DD}=10V,V_G=10V,L=0.5mH,Rg=25Ω

Test circuit

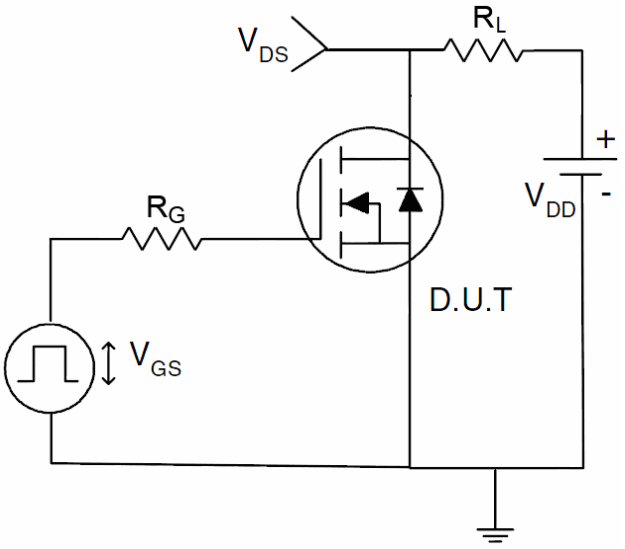
1）E_{AS} test Circuits



2）Gate charge test Circuit:



3）Switch Time Test Circuit：



Typical Electrical and Thermal Characteristics (Curves)

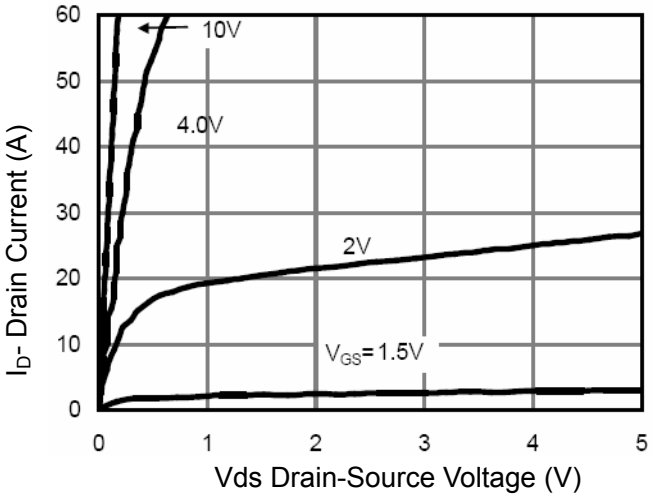


Figure 1 Output Characteristics

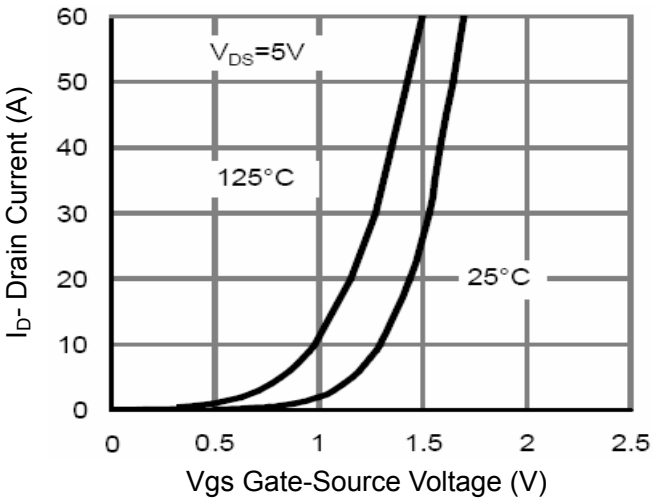


Figure 2 Transfer Characteristics

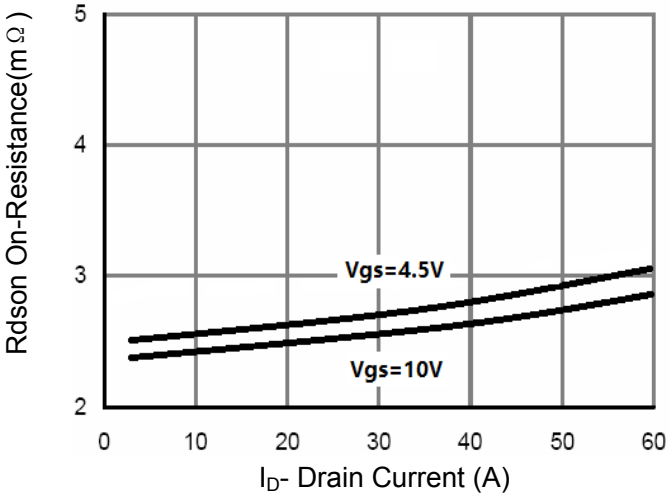


Figure 3 Rdson- Drain Current

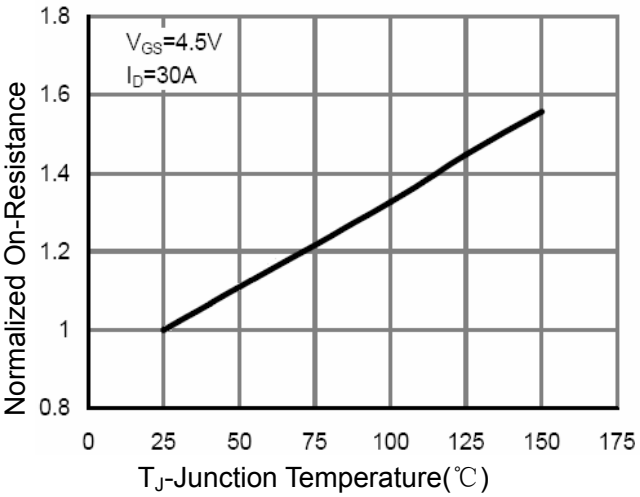


Figure 4 Rdson-Junction Temperature

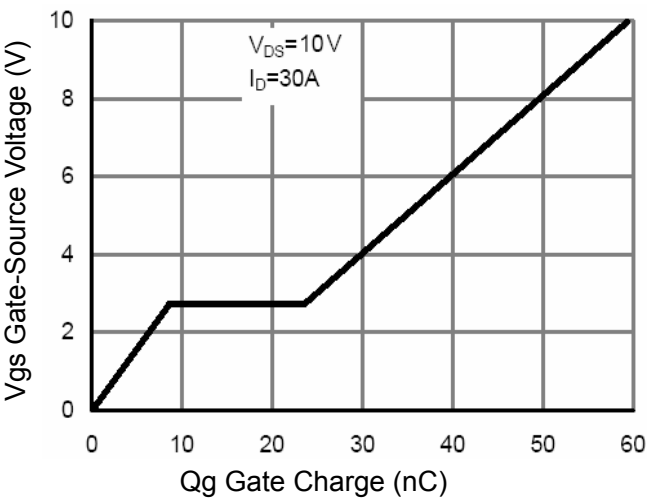


Figure 5 Gate Charge

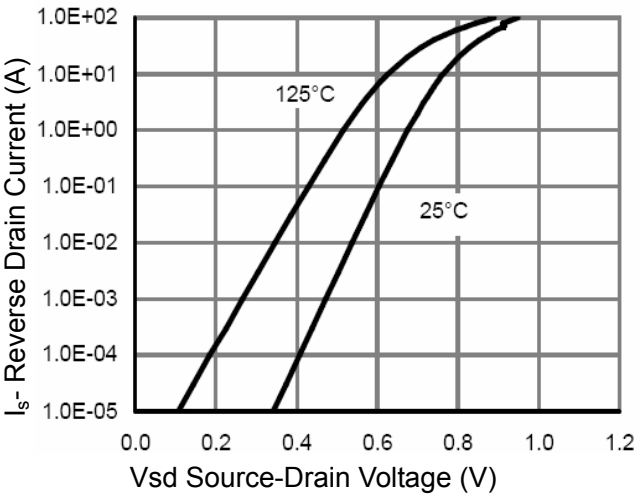


Figure 6 Source- Drain Diode Forward

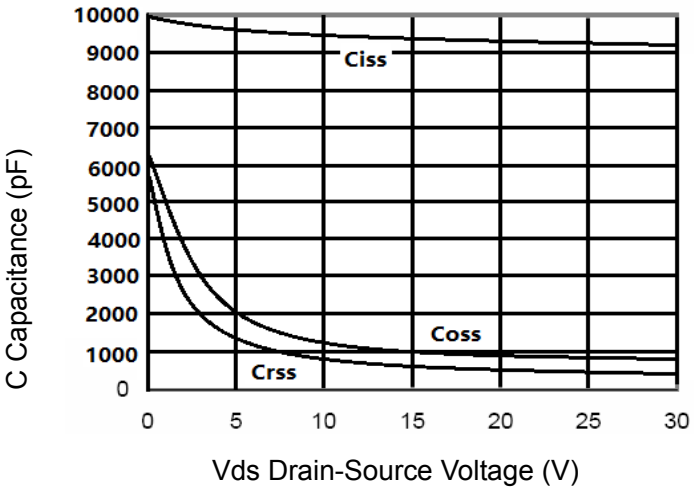


Figure 7 Capacitance vs Vds

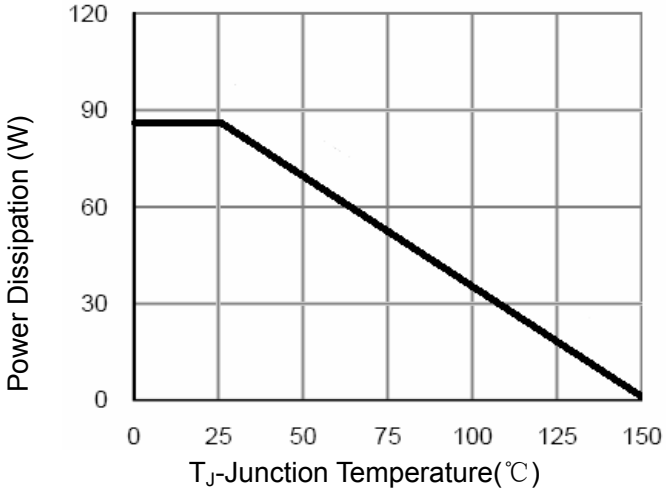


Figure 9 Power De-rating

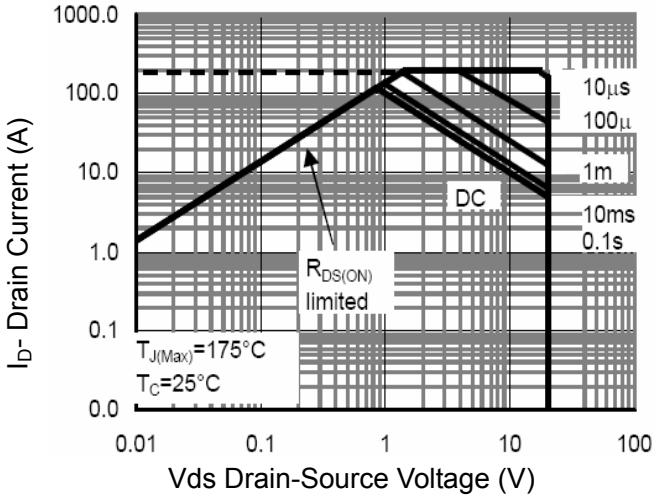


Figure 8 Safe Operation Area

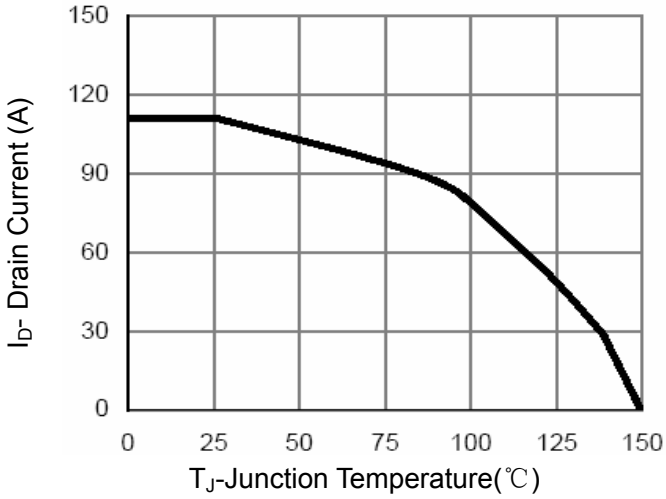


Figure 10 Current De-rating

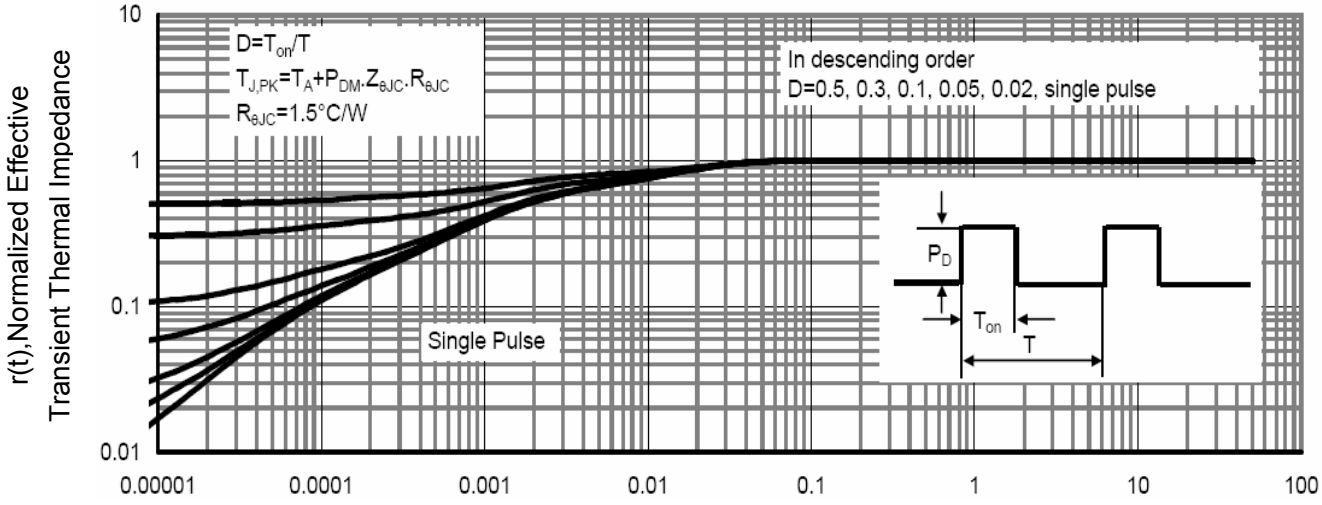
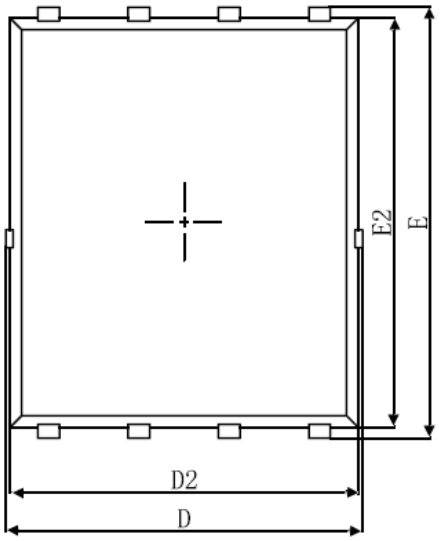
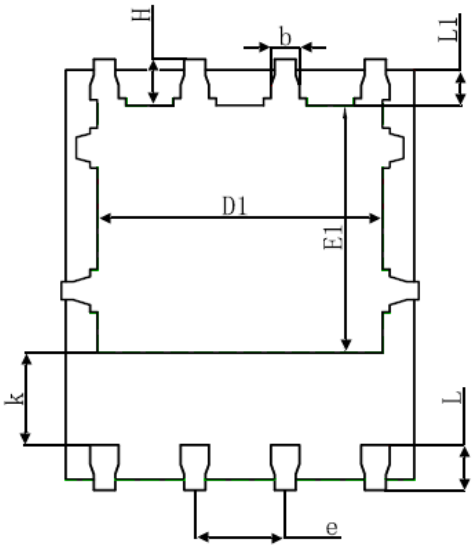


Figure 11 Normalized Maximum Transient Thermal Impedance

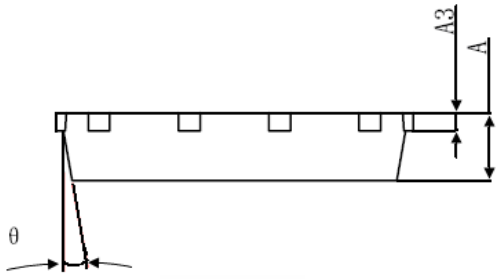
DFN5X6-8L Package Information



Top View
[顶视图]



Bottom View
[背视图]



Side View
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	8°	12°	8°	12°

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